

Company Identification
T = T-RAM

Architecture (a)
D = DDR
Q = QDR
P = Pipelined Burst
Z = Zero-turnaround (Zt)
S = Sigma SRAM

Die Revision (g)
A = 1st Die Revision
B = 2nd Die Revision
C = 3rd Die Revision

Speed Bin (hh)

10 = 100MHz	27 = 275MHz
12 = 120MHz	30 = 300MHz
13 = 130MHz	33 = 333MHz
15 = 150MHz	35 = 350MHz
16 = 167MHz	37 = 375MHz
20 = 200MHz	40 = 400MHz
22 = 225MHz	45 = 450MHz
25 = 250MHz	50 = 500MHz

Part Specific ID (i)
X = Lead Free Package
O = Regular Package

T a bb cc d ee f g - hh i j - k

Function (bb)
The product function is an 8 bit hex value made up of the following characters,

Bit[1:0]	00 = Not Applicable 01 = PL 10 = FT 11 = PL/FT
Bit[3:2]	00 = Not Applicable 01 = SCD 10 = DCD 11 = SCD/DCD Programmable
Bit[5:4]	00 = Not Applicable 01 = 1 CS 10 = 2 CS 11 = 3 CS
Bit 6	0 = No JTAG 1 = JTAG
Bit 7	Reserved

Product Designation (k)
B = Bulk
T = Tape and Reel
E = Engineering Sample
M = Mechanical Sample
Q = Qualification Sample

I/O Type (d)
C = CIO
S = SIO

Vdd/Vddq/Logic/Comment (f)
A = 2.5V/1.9V/HSTL/Extended
B = 2.5V/1.5V/HSTL
C = 1.8V/1.8V/HSTL/Extended
D = 1.8V/1.5V/HSTL
E = 1.5V/1.5V/HSTL
F = 1.5V/1.2V/HSTL
G = 1.2V/1.2V/HSTL
H = 3.3V/3.3V-2.5V CMOS
J = 3.3V/2.5V CMOS
K = 2.5V/2.5V CMOS
L = 2.5V/1.8V CMOS
M = 2.5V/1.5V CMOS
N = 1.8V/1.8V CMOS
P = 1.8V/1.5V CMOS
Q = 1.5V/1.5V CMOS

Package Type (i)
D = Die
A = 119 BGA
B = 153 BGA
C = 165 BGA
E = 209 BGA
F = 221 BGA
Q = 100 TQFP

Density (cc)
09 = 8M or 9M
18 = 16M or 18M
36 = 32M or 36M
72 = 64M or 72M
14 = 128M or 144M
28 = 256M or 288M
57 = 512M or 576M
01 = 1024M or 1152M
02 = 2048M or 2304M

Data Width (ee)
08 = x8
09 = x9
18 = x18
32 = x32
36 = x36
72 = x72
14 = x144